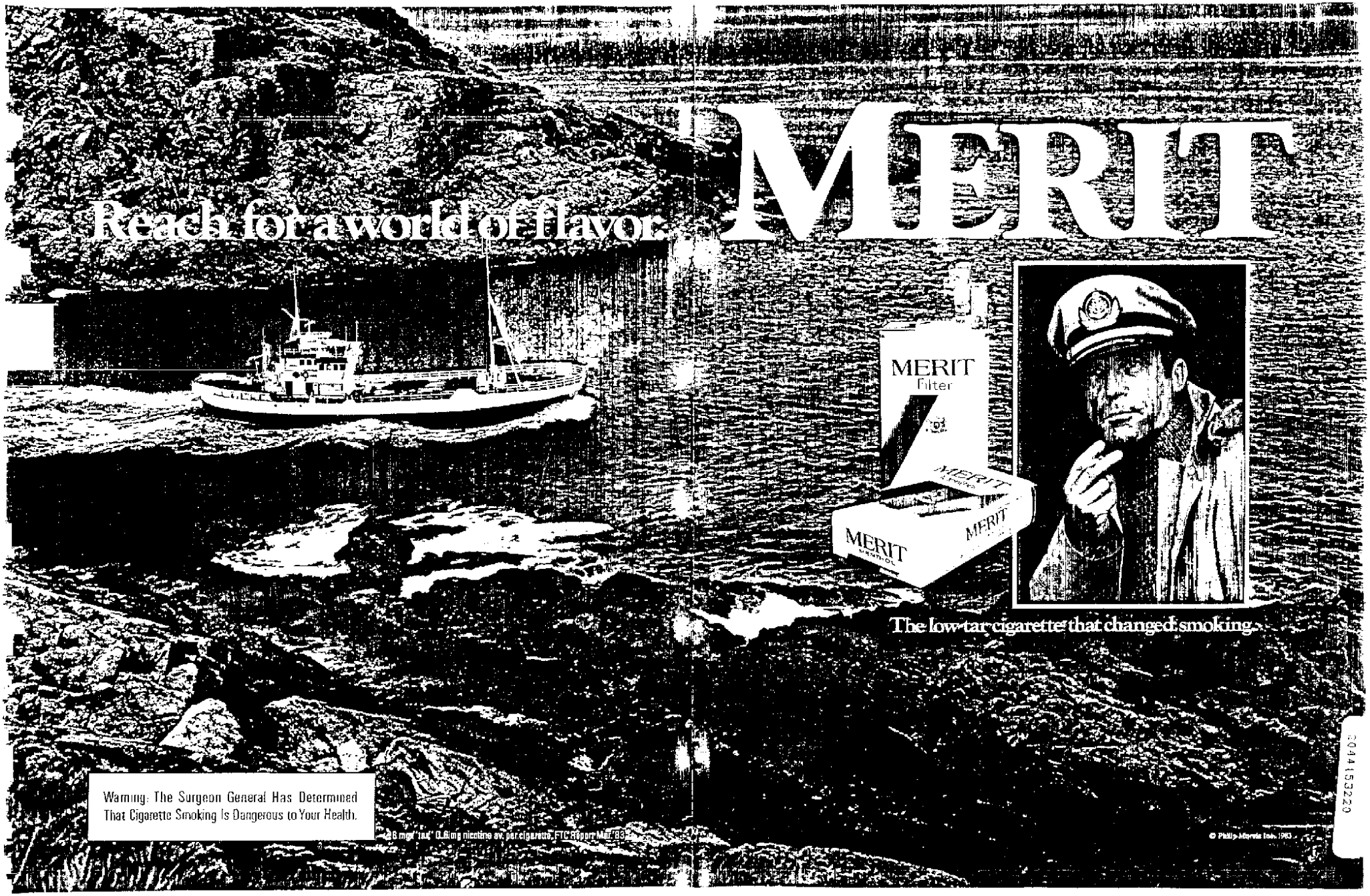


Source: https://www.industrydocuments.ucsf.edu/docs/kywn0004